GESMD5050RGBW Datasheet



Features:

- High Luminous Intensity
- Based on Blue/Green: InGaN, Red: AlGaInP technology
- Wide viewing angle: 120°
- Excellent performance and visibility
- Suitable for all SMT assembly methods
- IR reflow process compatible
- Environmental friendly; RoHS compliance

Typical Applications:

- Signal and Symbol Luminaire
- Indoor and Outdoor Displays
- Backlighting (illuminated advertising, general lighting)
- Interior Automotive Lighting

Absolute Maximum Ratings

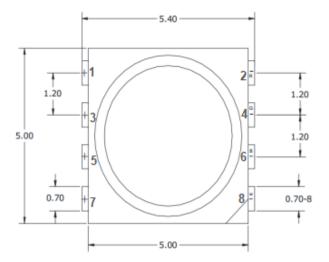
Absolute maximum ratings $(T_a=25^{\circ}C)$

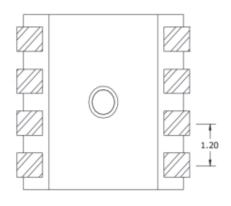
Parameter		Symbol	Value	Units
DC Forward Current	(R) (T/B)	I _F	35 30	mA
Pulse Forward Current (tp≤100μs, Duty cycle=0.25)		l _{pulse}	80 100	mA
Reverse Voltage		V_{R}	5	V
LED Junction Temperature		T,	115	°C
Operating Temperature		-	-40 ~ +85	°C
Storage Temperature		-	-40 ~ +125	°C
ESD Sensitivity (HBM)		V_{B}	2,000	V
Soldering Temperature		T_s	Reflow Soldering : 255~260°C/10~30sec Manual Soldering : 350°C/3sec	

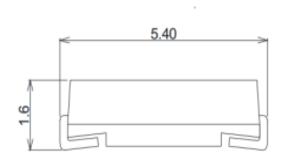
Electronic optical Parameters

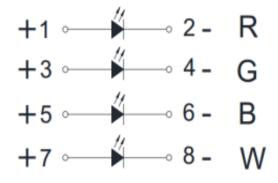
M/N: GESMD50	50RGBW (Ta=	:25℃)					
Parameter	Test condition	Symbol	Color	Value			Unit
		- J		Min	Тур	Max	
	If=20mA	λ	R	620	625	630	nm
Wavelength			G	520	525	530	nm
			В	460	465	470	nm
		ССТ	WW	2800	3000	3200	K
Color Temperature			NW	4000	4500	5000	K
			W	6000	6500	7000	K
Forward Voltage	If=20mA		R	1.8	2.0	2.2	V
		VF	G	3.0	3.2	3.4	V
		VI	В	3.0	3.2	3.4	V
			W	3.0	3.2	3.4	V
	If=20mA	lv	R	600	640	720	mcd
			G	1500	1650	1800	mcd
Luminous Intensity			В	400	450	500	mcd
			ww	1950	2000	2100	mcd
			NW	1980	2065	2170	mcd
			W	2000	2100	2200	mcd
View angle	If=20mA	θ			120		Deg
Reverse current	If=20mA	lr			10		uA

^{1.} The values are based on 1-die performance. 2.* $I_{\rm FP}$ condition: pulse width \leq 0.1 msec and duty \leq 1/10.



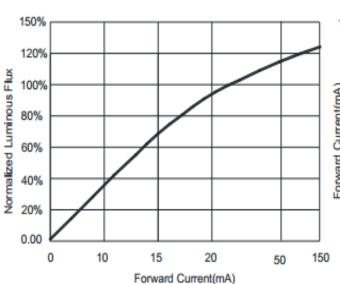




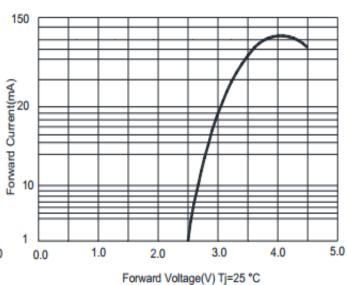


- Notes: 1. All dimensions are measured in mm.
- 2. Tolerance : \pm 0.2 mm

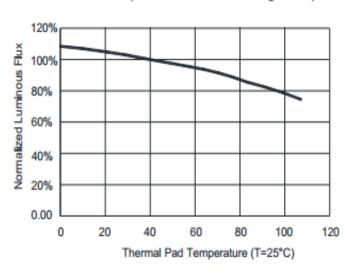
Typical Relative Luminous Flux vs. Forward Current



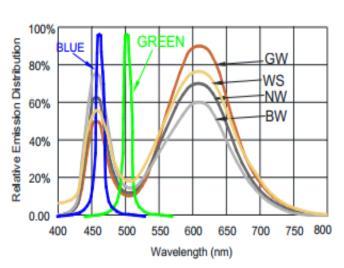
Forward Voltage vs. Forward Current



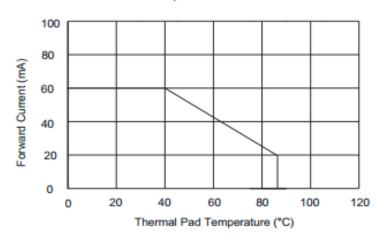
Thermal Pad Temperature vs. Relative Light Output



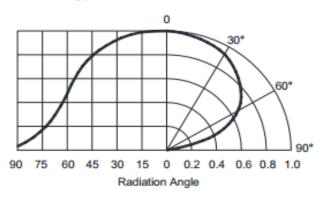
Wavelength Characteristics



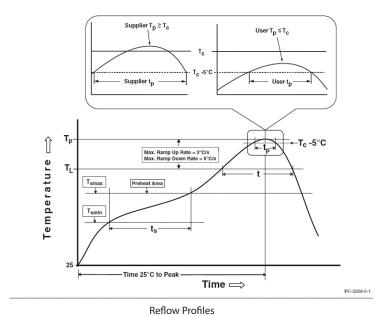
Thermal Pad Temperature vs. Forward Current



Typical Radiation Pattern 120°



The following reflow profile is from IPC/JEDEC J-STD-020D which provided here for reference.



Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150°C 200°C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3 °C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	217 °C 60-150 seconds
Peak package body temperature (Tp)*	255 °C ~260 °C *
Classification temperature (Tc)	260 °C
Time (tp)** within 5 °C of the specified classification temperature (Tc)	30** seconds
Average ramp-down rate (Tp to Tsmax)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

- 1. * Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

 2. ** Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.

Reliability

NO.	Test Item	Test Condition	Remark
1	Temperature Cycle	-40°C~100°C 30, 30, mins	100 Cycle
2	Thermal Shock	-40°C~100°C 15, 15 mins ≦ 10 sec	100 Cycle
3	Resistance to Soldering Heat	T _{SOL} =260°C, 30 sec	3 times
4	Moisture Resistance	25°C~65°C 90% RH 24 hrs / 1 cycle	10 Cycle
5	High-Temperature Storage	T _A =100°C	1,000 hrs
6	Humidity Heat Storage	T _A =85°C RH=85%	1,000 hrs
7	Low-Temperature Storage	T_A =-40°C	1,000 hrs
8	Operation Life test	25°C	1,000 hrs
9	High Temperature Operation Life test	85°C	1,000 hrs
10	High Humidity Heat Life Test	85°C, 85%RH	1,000 hrs
11	ON/OFF Test	30 sec ON, 30 sec OFF	1.5W times

Failure Criteria

ltem	Criteria for Judgment			
item	Min.	Max.		
Lumen Maintenance	85%	-		
∆ u'∨'	-	0.006		
Forward Voltage	-	Initial Data x 1.1		
Reverse Current	-	10 μΑ		
Resistance to Soldering Heat	No dead lamps or visual damage			

Product Packaging Information

